

2822

FIS920000242US1 (00750429AA)

PATENT APPLICATION

1



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

6/A Amold
11-20-02
A. W. Lee

In re Patent Application of

Lloyd G. Burrell et al.

Serial No.: 09/805,027

Group Art Unit: 2822

Filed: March 12, 2001

Examiner: M. Lewis

For: COPPER TO ALUMINUM INTERLAYER INTERCONNECT USING
STUD AND VIA LINER

Commissioner of Patents and Trademarks
Washington, D.C. 20231

RECEIVED
NOV 18 2002
TECHNOLOGY CENTER 2800

AMENDMENT UNDER 37 C. F. R. §1.111

Sir:

In response to the Office Action mailed August 14, 2002, please amend the above-identified application as follows:

In the claims:

Please substitute the following claim 1 for the like-numbered claim as originally filed. A marked up copy of this claim showing the current changes is attached as an appendix to this amendment.

- sub 2
1. (Amended) An integrated circuit including
- a patterned copper layer,
 - a patterned aluminum layer,
 - a stud connection in an opening in a layer of material between a location on said patterned copper layer and a location on said patterned aluminum layer, and
 - a liner in said opening and extending between said stud connection and said location on said patterned copper layer.